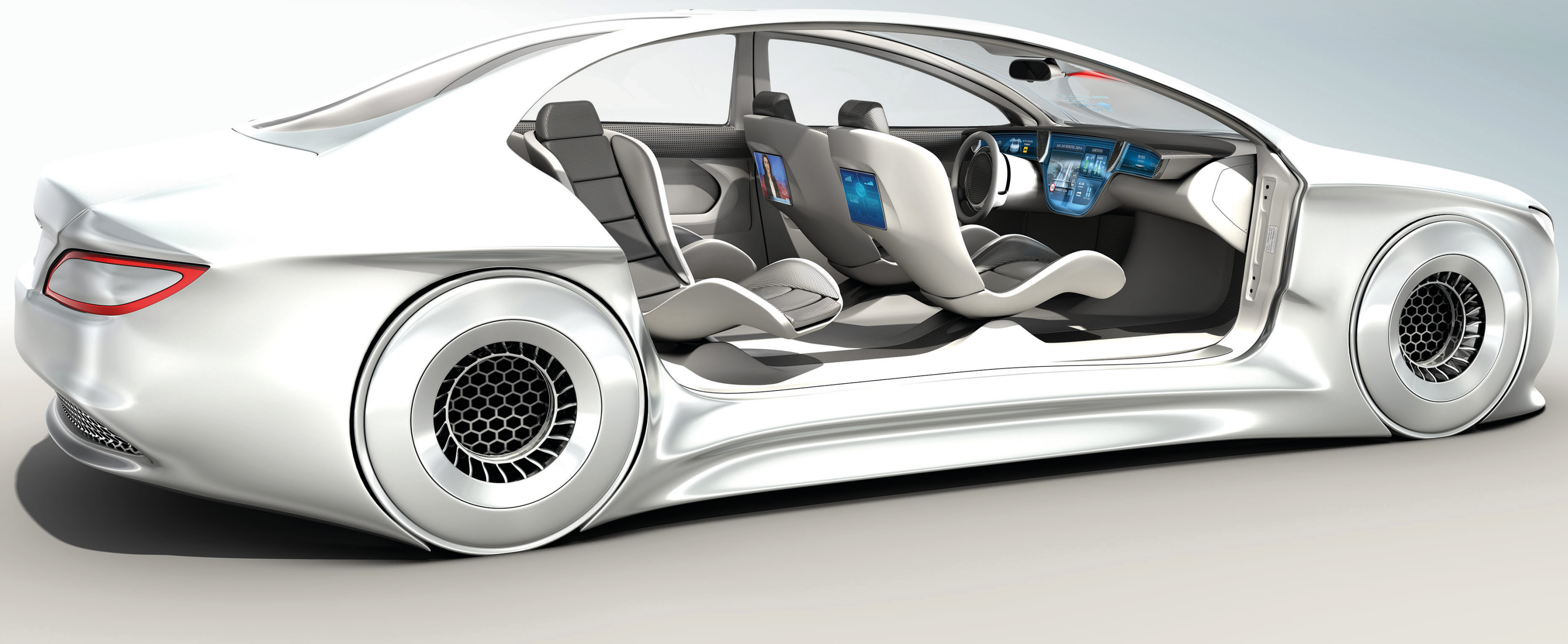
LOCTITE®

RAISING THE BAR ON THERMAL CONDUCTIVITY AND RELIABILITY



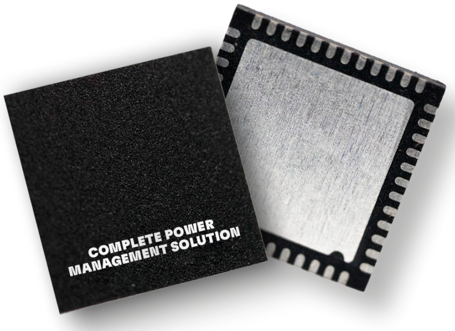
LOCTITE® *ABLESTIK* ABP 6395T delivers high thermal and electrical performance for demanding Power Management IC applications.

LOCTITE® *ABLESTIK* ABP 6395T is an electrically conductive die attach adhesive designed for high thermal conductivity (~30 W/m-K) and high reliability package applications. The material is formulated with good thermal conductivity for heat management, along with excellent electrical conductivity to achieve low on resistance - RDS (on) - in power ICs.

Sustainable principles and safety have also been prioritized in the development of this material, which has low VOCs and achieves excellent performance with comparatively low silver content. Engineered to adhere to die with or without back side metallization (BSM), LOCTITE® *ABLESTIK* ABP 6395T is compatible with a wide variety of lead frame surfaces, including Cu, Ag and PPF.

Key Applications:

- Typically recommended for Power Management ICs used in Motor Control, Voltage regulators, Battery Management, and other applications in Consumer Electronics, Automotive and Industrial



Henkel

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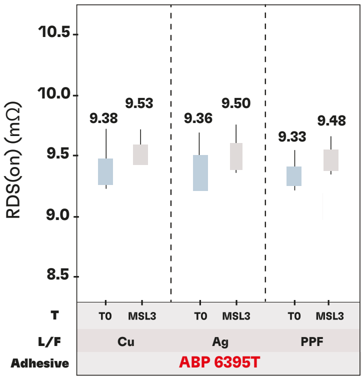
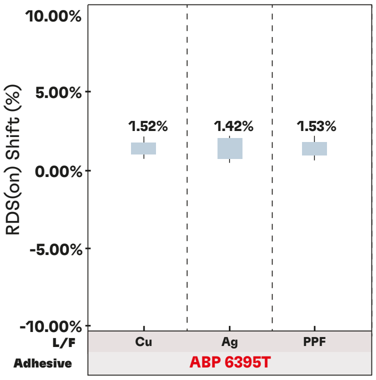
Technical Information

LOCTITE® *ABLESTIK* ABP 6395T

Technology Filler		Epoxy Silver
Thixotropic Index (0.5/5 rpm)		6.2
Viscosity, Brookfield CP51 25°C mPas (cP)		8,500
Modulus (GPa)	25°C	8.1
	15°C	1.4
	25°C	1.1
Bulk Thermal Conductivity (W/m-k)		30.0
Volume Resistivity (Ohm-cm)		$4.2x10^{-5}$
Recommended cure profile		30 min. ramp to 200°C + 30 min. @ 200°C in N2 or air
Weight Loss on Cure, by TGA (%)		4.1
Work Life at 25°C (Hours)		24
Storage Life (-40°C)		1 year





Key Features and Benefits:

High Reliability

- Meets challenging automotive grade reliability and MSL 1 reliability on die sizes < 3.0 mm x 3.0 mm
- High die shear strength on various substrate finishes including Ag, Cu and PPF

Best-in-Class Thermal and Electrical Performance

- Bulk thermal conductivity up to 30 W/m-K
- Excellent electrical conductivity and in-package RDS(on) performance, stable RDS(on) after 1,000 thermal cycles

Workability/Processability

- No RBO
- Standard die attach dispensing process, with no silver settling or separation
- Stable, consistent dispense performance for 24 hrs.

Health and Safety

- Reduced VOCs versus other high thermal conductivity die attach pastes

Want to find out more about high-performance conductive die attach designed for high reliability?

Get in touch with our technology specialists to learn about our portfolio of high thermal die attach paste materials.

henkel-adhesives.com/electronics

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Scan the QR code above for product inquiry.